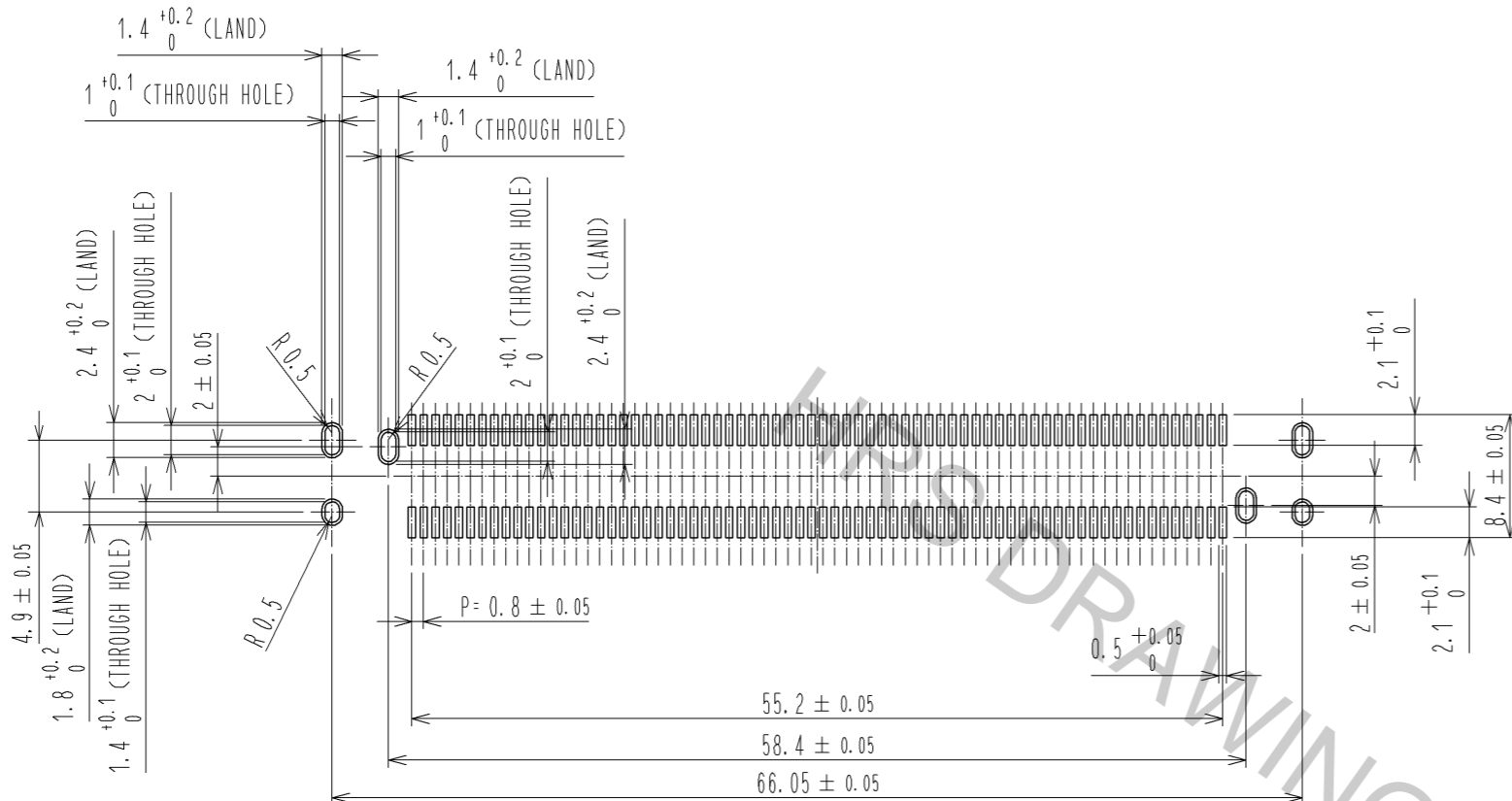


- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 - ③ MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 - ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2) REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 - ⑤ THIS IS PACKAGED IN TRAY. (30pcs/TRAY)
 - ⑥ BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 - ⑦ THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

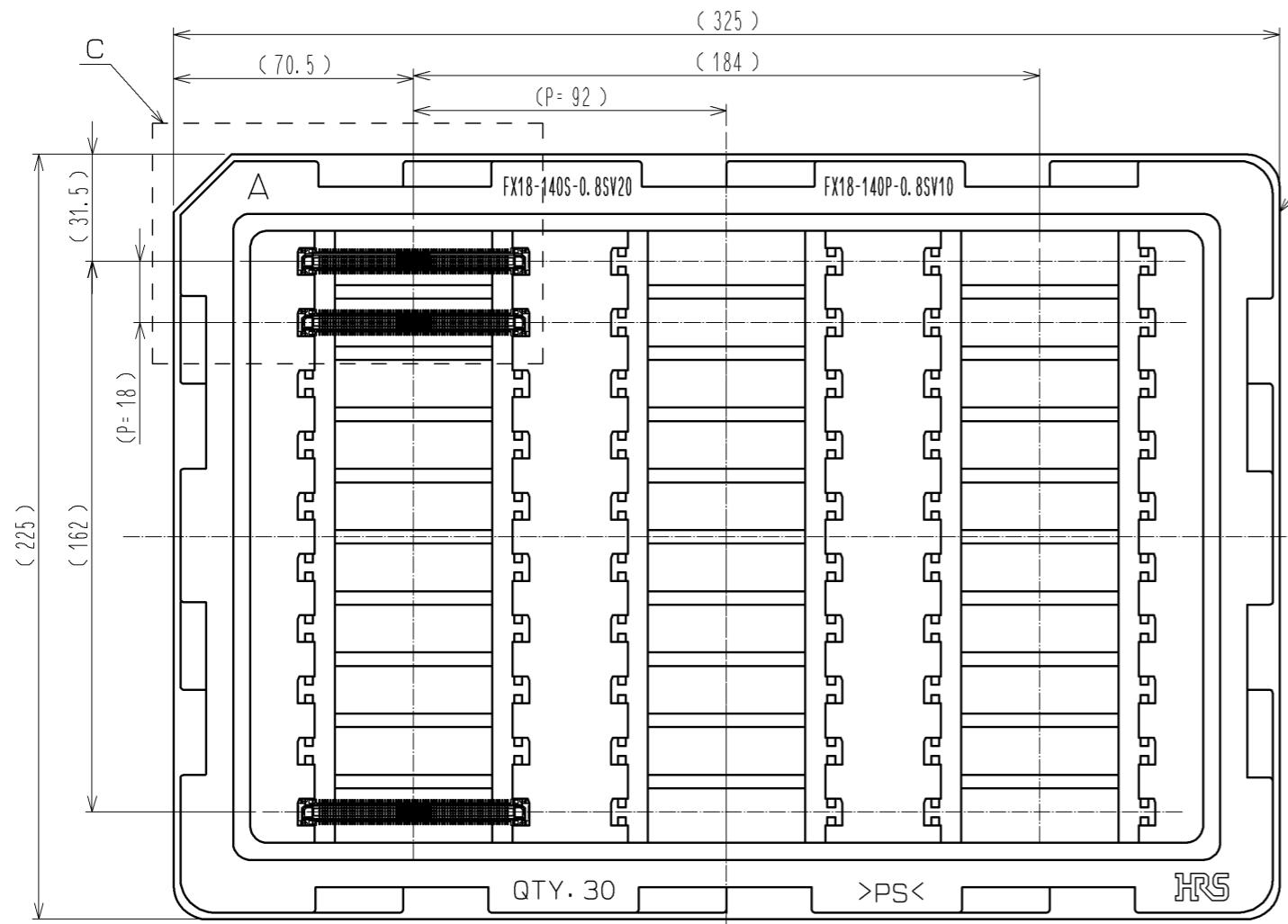
7	POLYIMIDE						
6	POLYSTYRENE						
5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm					
		LEAD AREA:TIN-PLATING 1 μm					
		UNDER PLATING:NICKEL 1.3 μm					
4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm					
		LEAD AREA:TIN-PLATING 1 μm					
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm					
		LEAD AREA:GOLD 0.03 μm					
		UNDER PLATING:NICKEL 1.3 μm					
2	POLYAMIDE	BLACK UL94V-0					
1	POLYAMIDE	BLACK UL94V-0					
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS

UNITS	mm	SCALE	2 : 1	COUNT	△	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
APPROVED : HS. OKAWA		12.06.12		DRAWING NO.		EDC3-343468-00			
CHECKED : KI. HIROKAWA		12.06.12		PART NO.		FX18-140S-0.8SV20			
DESIGNED : AH. EDASHIGE		12.06.12		CODE NO.		CL579-0039-5-00			
DRAWN : AH. EDASHIGE		12.06.12							

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
 (PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)



5 DRAWING FOR PACKING(1:2)

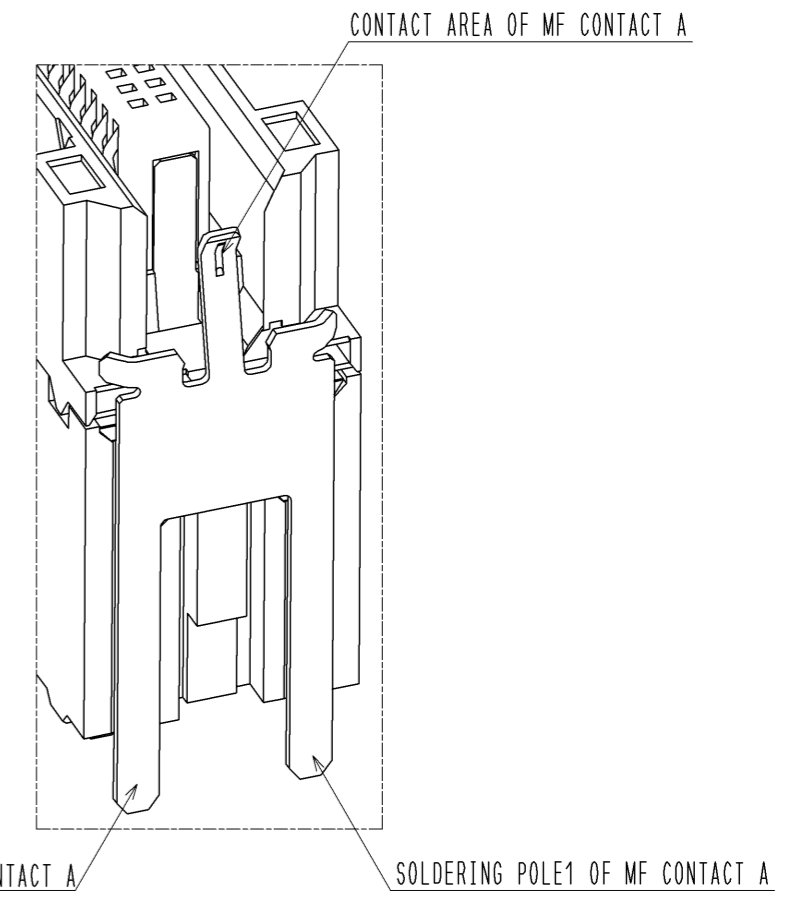


QTY. 30

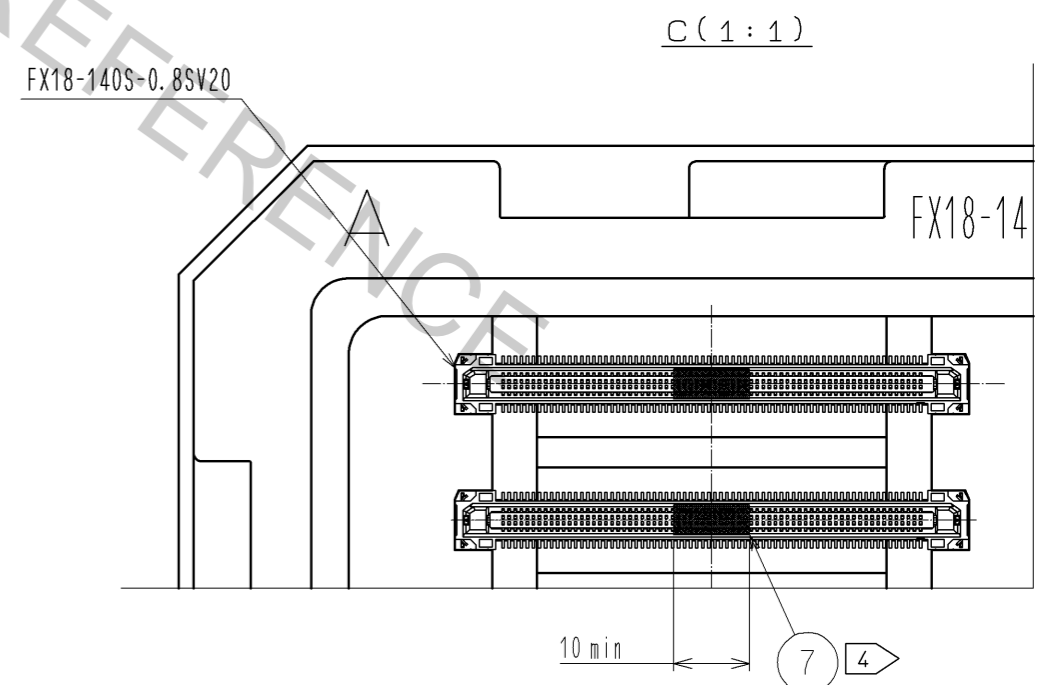
>PS<

HRS

8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES. BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS	DRAWING NO.	EDC3-343468-00
	PART NO.	FX18-140S-0.8SV20
	CODE NO.	CL579-0039-5-00
		△ 2/2